

#### 400 Volt, 3.6Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

#### Product Summary

| Part Number  | BV <sub>DSS</sub> | R <sub>DS(on)</sub> | I <sub>D</sub> |
|--------------|-------------------|---------------------|----------------|
| JANTX2N6786  | 400V              | 3.6Ω                | 1.25A          |
| JANTXV2N6786 |                   |                     |                |

#### Features:

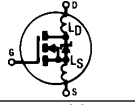
- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed

#### Absolute Maximum Ratings

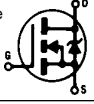
|  | Parameter                   | JANTX2N6786, JANTXV2N6786                          | Units |
|--|-----------------------------|--|-------|
| I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 25°C  | Continuous Drain Current    | 1.25   | A     |
| I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 100°C | Continuous Drain Current    | 0.80   |       |
| I <sub>DM</sub>  | Pulsed Drain Current ①      | 5.0  |       |
| P <sub>D</sub> @ T <sub>C</sub> = 25°C                         | Max. Power Dissipation      | 15   | W     |
|  | Linear Derating Factor      | 0.12   | W/K ⑤ |
| V <sub>GS</sub>  | Gate-to-Source Voltage      | ±20  | V     |
| dv/dt  | Peak Diode Recovery dv/dt ③ | 4.0  | V/ns  |
| T <sub>J</sub>   | Operating Junction          | -55 to 150   | °C    |
| T <sub>STG</sub>   | Storage Temperature Range   |  |       |
|  | Lead Temperature            | 300 (0.063 in. (1.6mm) from case for 10.5 seconds) |       |
|  | Weight                      | 0.98 (typical)                                     |       |

# JANTX2N6786, JANTXV2N6786 Device

## Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

|                              | Parameter                                    | Min. | Typ. | Max. | Units    | Test Conditions   |
|------------------------------|--|------|------|------|----------|---|
| $BV_{DSS}$                   | Drain-to-Source Breakdown Voltage            | 400  | —    | —    | V        | $V_{GS} = 0V, I_D = 1.0 \text{ mA}$   |
| $\Delta BV_{DSS}/\Delta T_J$ | Temperature Coefficient of Breakdown Voltage | —    | 0.37 | —    | V/°C     | Reference to 25°C, $I_D = 1.0 \text{ mA}$   |
| RDS(on)                      | Static Drain-to-Source                       | —    | —    | 3.6  | $\Omega$ | $V_{GS} = 10V, I_D = 0.80A$ ④   |
|                              | On-State Resistance                          | —    | —    | 4.15 |          |   |
| $V_{GS(th)}$                 | Gate Threshold Voltage                       | 2.0  | —    | 4.0  | V        | $V_{DS} = V_{GS}, I_D = 250\mu A$   |
| $g_{fs}$                     | Forward Transconductance                     | 0.7  | —    | —    | S (r)    | $V_{DS} > 15V, I_{DS} = 0.80A$ ④  |
| IDSS                         | Zero Gate Voltage Drain Current              | —    | —    | 25   | $\mu A$  | $V_{DS} = 0.8 \times \text{Max Rating}, V_{GS} = 0V$  |
|                              |  | —    | —    | 250  |          |   |
| IGSS                         | Gate-to-Source Leakage Forward               | —    | —    | 100  | nA       | $V_{GS} = 20V$  |
| IGSS                         | Gate-to-Source Leakage Reverse               | —    | —    | -100 | nA       | $V_{GS} = -20V$   |
| Qg                           | Total Gate Charge                            | 6.7  | —    | 8.4  | nC       | $V_{GS} = 10V, I_D = 1.25A$<br>$V_{DS} = \text{Max. Rating} \times 0.5$<br>see figures 6 and 13   |
| Qgs                          | Gate-to-Source Charge                        | 0.2  | —    | 1.5  |          |   |
| Qgd                          | Gate-to-Drain ("Miller") Charge              | 3.5  | —    | 5.0  |          |   |
| td(on)                       | Turn-On Delay Time                           | —    | —    | 15   | ns       | $V_{DD} = 200V, I_D = 1.25A,$<br>$R_G = 7.5\Omega, V_{GS} = 10V$<br><br>see figure 10   |
| tr                           | Rise Time                                    | —    | —    | 20   |          |   |
| td(off)                      | Turn-Off Delay Time                          | —    | —    | 35   |          |   |
| tf                           | Fall Time                                    | —    | —    | 30   |          |   |
| LD                           | Internal Drain Inductance                    | —    | 5.0  | —    | nH       | Measured from the drain lead, 6mm (0.25 in.) from package to center of die.<br><br>Modified MOSFET symbol showing the internal inductances.  |
| LS                           | Internal Source Inductance                   | —    | 15   | —    |          |   |
| Ciss                         | Input Capacitance                            | —    | 170  | —    | pF       | $V_{GS} = 0V, V_{DS} = 25V$<br>$f = 1.0 \text{ MHz}$<br>see figure 5  |
| Coss                         | Output Capacitance                           | —    | 49   | —    |          |   |
| Crss                         | Reverse Transfer Capacitance                 | —    | 10   | —    |          |   |

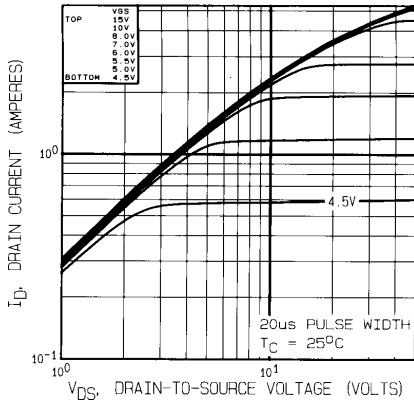
## Source-Drain Diode Ratings and Characteristics

|     | Parameter                              | Min.  | Typ. | Max. | Units   | Test Conditions   |
|-----|--|---|------|------|---------|---|
| IS  | Continuous Source Current (Body Diode) | —   | —    | 1.25 | A       | Modified MOSFET symbol showing the integral reverse p-n junction rectifier.  |
| ISM | Pulse Source Current (Body Diode) ①    | —   | —    | 5.0  |         |   |
| VSD | Diode Forward Voltage                  | —   | —    | 1.4  | V       | $T_J = 25^\circ C, I_S = 1.25A, V_{GS} = 0V$ ④  |
| trr | Reverse Recovery Time                  | —   | —    | 540  | ns      | $T_J = 25^\circ C, I_F = 1.25A, di/dt \leq 100A/\mu s$<br>$V_{DD} \leq 50V$ ④   |
| QRR | Reverse Recovery Charge                | —   | —    | 4.5  | $\mu C$ |   |
| ton | Forward Turn-On Time                   | Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by LS + LD. |      |      |         |   |

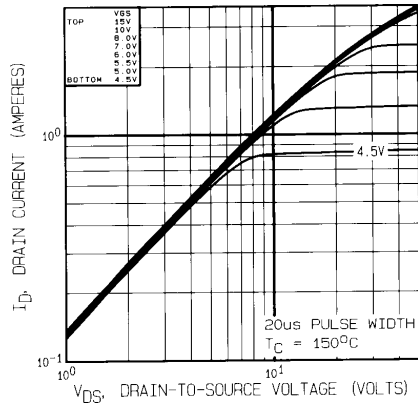
## Thermal Resistance

|       | Parameter           | Min. | Typ. | Max. | Units | Test Conditions      |
|-------|---------------------|------|------|------|-------|----------------------|
| RthJC | Junction-to-Case    | —    | —    | 8.3  | K/W   | Typical socket mount |
| RthJA | Junction-to-Ambient | —    | —    | 175  |       |                      |

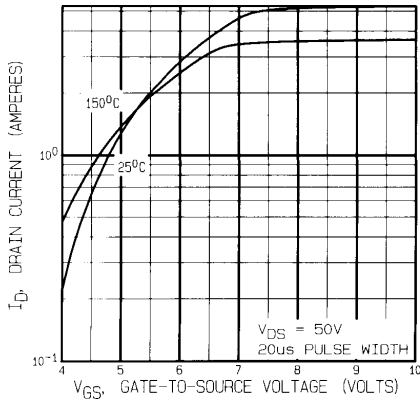
# JANTX2N6786, JANTXV2N6786 Device



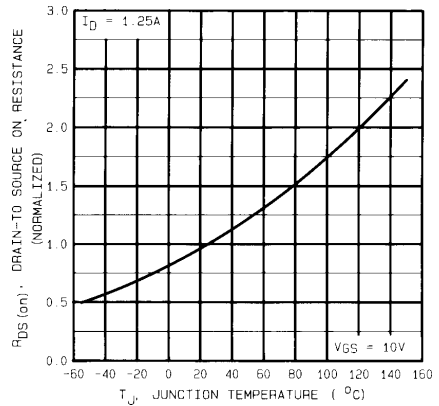
**Fig. 1 — Typical Output Characteristics**  
 $T_C = 25^\circ\text{C}$



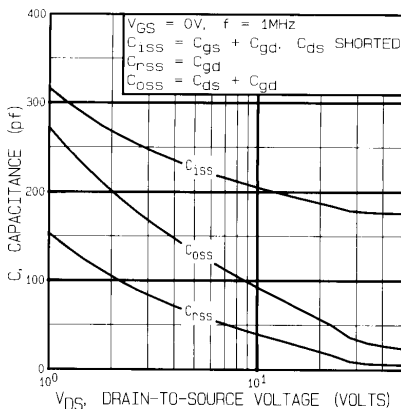
**Fig. 2 — Typical Output Characteristics**  
 $T_C = 150^\circ\text{C}$



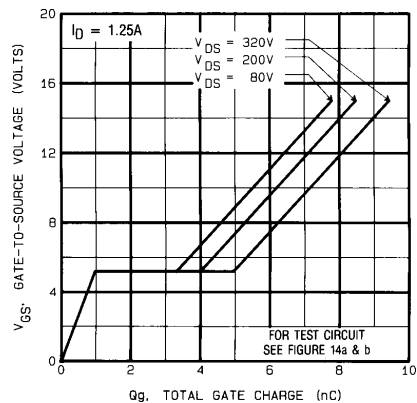
**Fig. 3 — Typical Transfer Characteristics**



**Fig. 4 — Normalized On-Resistance Vs. Temperature**

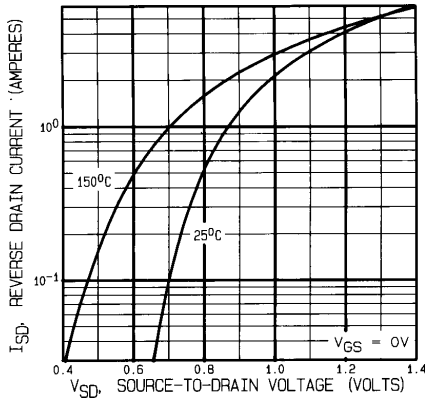


**Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage**

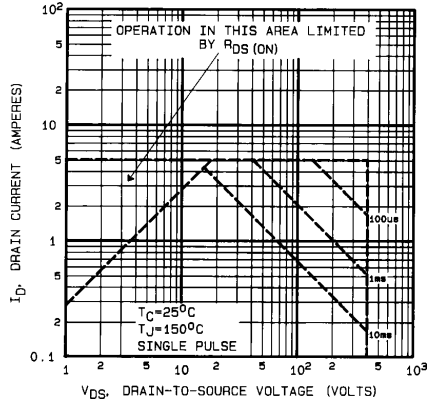


**Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage**

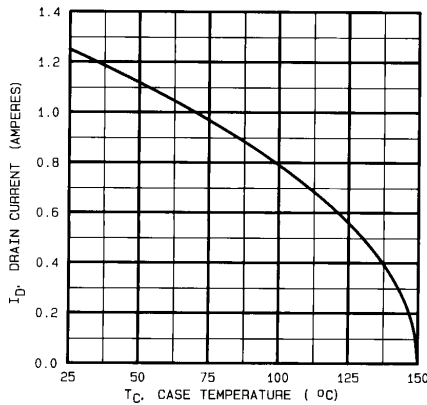
# JANTX2N6786, JANTXV2N6786 Device



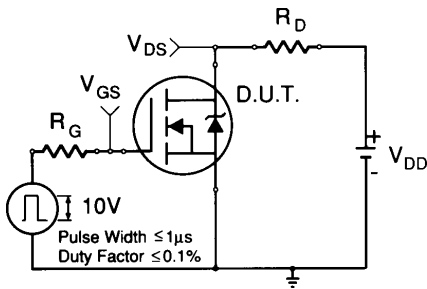
**Fig. 7 — Typical Source-to-Drain Diode Forward Voltage**



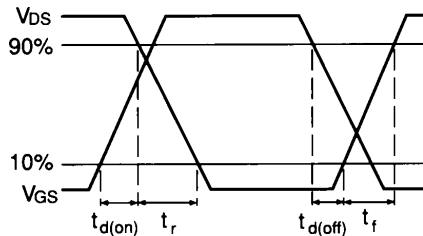
**Fig. 8 — Maximum Safe Operating Area**



**Fig. 9 — Maximum Drain Current Vs. Case Temperature**



**Fig. 10a — Switching Time Test Circuit**



**Fig. 10b — Switching Time Waveforms**

# JANTX2N6786, JANTXV2N6786 Device

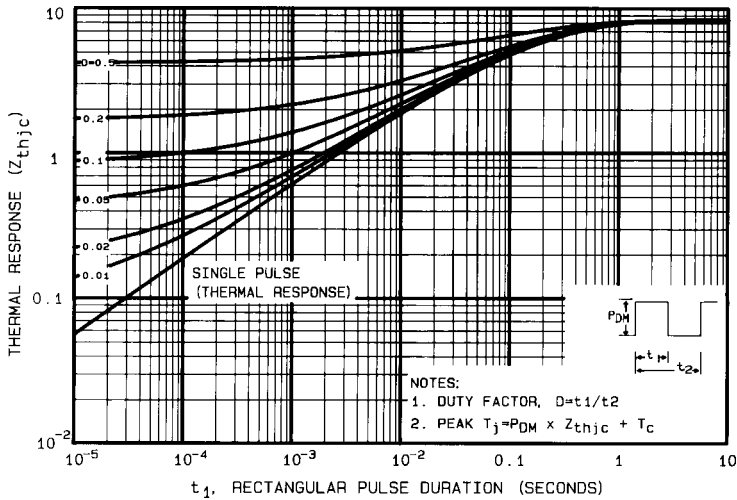


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

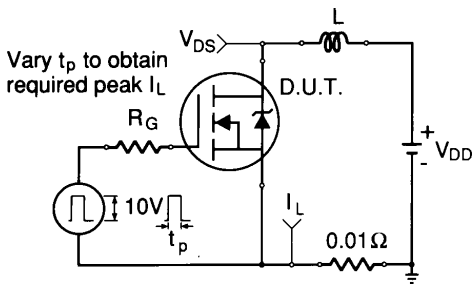


Fig. 12a — Unclamped Inductive Test Circuit

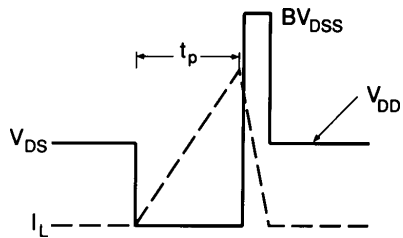


Fig. 12b — Unclamped Inductive Waveforms

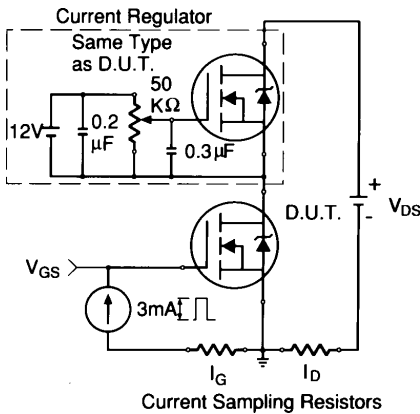


Fig. 13a — Gate Charge Test Circuit

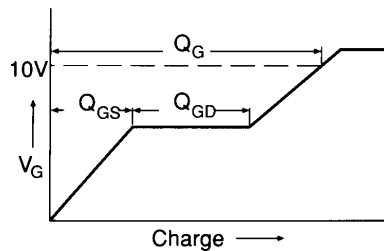
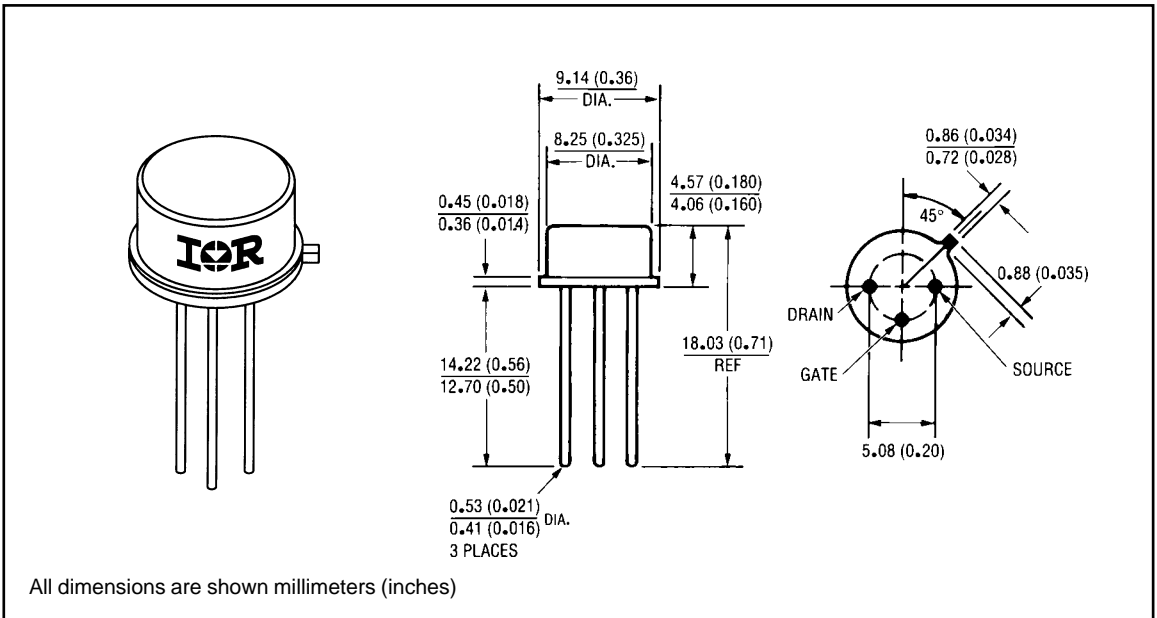


Fig. 13b — Basic Gate Charge Waveform

## JANTX2N6786, JANTXV2N6786 Device

- ① Repetitive Rating; Pulse width limited by maximum junction temperature. (see figure 11)
- ② @  $V_{DD} = 50V$ , Starting  $T_J = 25^\circ C$ ,  
 $EAS = [0.5 * L * (I_L^2) * [BV_{DSS}/(BV_{DSS}-V_{DD})]]$   
 Peak  $I_L = 1.25A$ ,  $V_{GS} = 10V$ ,  $25 \leq R_G \leq 200\Omega$
- ③  $ISD \leq 1.25A$ ,  $di/dt \leq 40A/\mu s$ ,  
 $V_{DD} \leq BV_{DSS}$ ,  $T_J \leq 150^\circ C$
- ④ Pulse width  $\leq 300 \mu s$ ; Duty Cycle  $\leq 2\%$
- ⑤  $K/W = ^\circ C/W$   
 $W/K = W/^\circ C$

### Case Outline and Dimensions — TO-205AF (Modified TO-39)



International  
**IOR** Rectifier

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Data and specifications subject to change without notice. 10/96